

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		add\$4 same (scribe adj1 mark\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:29
L1	1413	(235/494.ccls. and depth) and pit\$235/494.ccls.	USPAT US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR OR	OFF OFF	2002/01/16 10:20 2005/11/21 18:12
L2	0	1 and (wafer same coat\$4 same (sapphire carbide))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 19:20
L3	811	257/797.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 18:13
L4	0	3 and (wafer same coat\$4 same (sapphire carbide))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 18:14
L5	113	483/401,462,975,15,16.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 18:21
L6	0	5 and (wafer same coat\$4 same (sapphire carbide))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 18:14
L7	708	1 and (read\$4 same process\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 19:01

L8	116	3 and (read\$4 same process\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 19:22
L9	2337	1 3 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 19:20
L10	1	9 and (wafer and coat\$4 and (sapphire carbide)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 19:21
L11	125	9 and (read\$4 same process\$4).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 19:22
S1	634	235/494.ccls.	USPAT	OR	OFF	2005/11/21 18:12
S2	8	235/494.ccls. and wafer	USPAT	OR	OFF	2002/08/26 07:54
S3	582	438/401,462,975.ccls.	USPAT	OR	OFF	2002/01/04 09:09
S4	11	438/401,462,975.ccls. and ion adj implant	USPAT	OR	OFF	2002/01/04 09:10
S5	52	wafer adj pit\$2	USPAT	OR	OFF	2002/01/04 09:10
S6	932	wafer adj25 pit\$2	USPAT	OR	OFF	2002/01/04 09:13
S7	266	(wafer adj25 pit\$2) same pattern	USPAT	OR	OFF	2002/01/04 09:13
S8	6	((wafer adj25 pit\$2) same pattern) same read\$4	USPAT	OR	OFF	2002/01/15 09:27
S9	180	wafer adj25 pits	USPAT	OR	OFF	2002/01/04 09:13
S10	20	(wafer adj25 pits) same pattern	USPAT	OR	OFF	2002/01/04 09:18
S11	128	wafer adj identification	USPAT	OR	OFF	2002/01/16 10:25
S12	0	(wafer adj identification) same pits	USPAT	OR	OFF	2002/01/04 09:19
S13	4	(wafer adj identification) and pits	USPAT	OR	OFF	2002/01/04 09:19
S14	2554	hattori.in.	USPAT	OR	OFF	2002/01/15 08:54
S15	17	hattori-takeshi.in.	USPAT	OR	OFF	2002/01/16 10:32
S16	1	("4585931").PN.	USPAT; USOCR	OR	OFF	2002/01/15 09:00
S17	26	"4585931".URPN.	USPAT	OR	OFF	2002/01/15 08:59
S18	1	"4585931".URPN. and groove	USPAT	OR	OFF	2002/01/15 09:01

S19	17	("3112850" "3597045" "4010355" "4418467" "4510673" "4543464" "4585931" "4794238" "4812631" "4825093" "5109149" "5175774" "5229306" "5329090" "5821167" "5876819" "6004405").PN.	USPAT	OR	OFF	2002/01/16 07:14
S20	0	(wafer adj25 (ion adj implant)) adj (pitch pit)	USPAT	OR	ON	2002/08/26 14:40
S21	1	(wafer adj25 (ion adj implant)) same (pitch pit)	USPAT	OR	ON	2002/01/15 09:28
S22	131	wafer adj25 (ion adj implant)	USPAT	OR	OFF	2002/01/15 13:00
S23	0	wafer adj25 (ion adj implant adj5 contrast)	USPAT	OR	OFF	2002/01/15 09:35
S24	21	wafer adj25 (ion adj implant) and contrast	USPAT	OR	OFF	2002/01/16 07:10
S25	17	wafer adj25 (ion adj implant) and (pitch pit groove)	USPAT	OR	OFF	2002/01/15 13:18
S26	1242	wafer adj25 identif\$	USPAT	OR	OFF	2002/01/15 13:18
S27	242	(wafer adj25 identif\$) and (pitch pit groove)	USPAT	OR	OFF	2002/01/15 13:18
S28	31	((wafer adj25 identif\$) and (pitch pit groove)) and reader	USPAT	OR	OFF	2002/01/15 13:24
S29	0	wafer adj25 ((ion adj implant) near contrast)	USPAT	OR	OFF	2002/01/16 07:10
S30	0	wafer adj25 ((ion adj implant) same contrast)	USPAT	OR	OFF	2002/01/16 07:11
S31	24	((ion adj implant) same contrast)	USPAT	OR	OFF	2002/01/16 07:12
S32	0	(ion adj implant) adj25 reader	USPAT	OR	OFF	2002/01/16 07:12
S33	0	reader adj25 (ion adj implant)	USPAT	OR	OFF	2002/01/16 07:13
S34	2	reader same (ion adj implant)	USPAT	OR	OFF	2002/01/16 07:13
S35	0	(("3112850" "3597045" "4010355" "4418467" "4510673" "4543464" "4585931" "4794238" "4812631" "4825093" "5109149" "5175774" "5229306" "5329090" "5821167" "5876819" "6004405").PN.) and (ion adj implant)	USPAT	OR	OFF	2002/01/16 07:14

S36	17	(("3112850" "3597045" "4010355" "4418467" "4510673" "4543464" "4585931" "4794238" "4812631" "4825093" "5109149" "5175774" "5229306" "5329090" "5821167" "5876819" "6004405").PN.) and (ion a)	USPAT	OR	OFF	2002/01/16 07:14
S37	2	(("3112850" "3597045" "4010355" "4418467" "4510673" "4543464" "4585931" "4794238" "4812631" "4825093" "5109149" "5175774" "5229306" "5329090" "5821167" "5876819" "6004405").PN.) and (ion)	USPAT	OR	OFF	2002/01/16 07:24
S38	21	"4418467".URPN.	USPAT	OR	OFF	2002/08/26 14:00
S39	4	"4418467".URPN. and ion	USPAT	OR	OFF	2002/01/16 07:24
S40	48	235/494.ccls. and depth	USPAT	OR	OFF	2002/01/16 10:20
S41	1	wafer adj identification adj25 notch\$	USPAT	OR	OFF	2002/01/16 10:26
S42	770	wafer adj25 notch\$	USPAT	OR	OFF	2002/01/16 10:42
S43	4	(wafer adj25 notch\$) and (ion adj implant)	USPAT	OR	OFF	2002/01/16 10:29
S44	14	("4841346" "4859620" "4901129" "5217910" "5258319" "5372957" "5409848" "5413945" "5500379" "5512498" "5532176" "5686324" "5716862" "5753556").PN.	USPAT	OR	OFF	2002/01/16 13:59
S45	0	(("4841346" "4859620" "4901129" "5217910" "5258319" "5372957" "5409848" "5413945" "5500379" "5512498" "5532176" "5686324" "5716862" "5753556").PN.) and (notch\$2 pit\$2)	USPAT	OR	OFF	2002/01/16 10:30
S46	2	hattori-takeshi.in. and notch\$2	USPAT	OR	OFF	2002/01/16 10:40
S47	371	KATSURA.in.	USPAT	OR	OFF	2002/01/16 10:40
S48	8	KATSURA.in. and wafer	USPAT	OR	OFF	2002/01/16 10:47
S49	1	(wafer adj25 notch\$) and 235/494.ccls.	USPAT	OR	OFF	2002/01/16 10:42
S50	2	SATO-ETSURO.in.	USPAT	OR	OFF	2002/01/16 10:47
S51	32	YAJIMA.in. and wafer	USPAT	OR	OFF	2002/01/16 10:59

S52	808	wafer and identification and (pit\$2 notch\$3)	USPAT; EPO; JPO	OR	OFF	2002/01/16 12:31
S53	9	(wafer and identification and (pit\$2 notch\$3)) and (ion adj25 implant)	USPAT; EPO; JPO	OR	OFF	2002/01/16 11:00
S54	40	wafer adj identification and (pit\$2 notch\$3)	USPAT; EPO; JPO	OR	OFF	2002/01/16 11:01
S55	5	wafer and identification and (pit\$2 notch\$3) and boule	USPAT; EPO; JPO	OR	OFF	2002/01/16 12:32
S56	7584	inoue.in.	USPAT	OR	OFF	2002/01/16 13:14
S57	307	inoue.in. and wafer	USPAT	OR	OFF	2002/01/16 13:14
S58	8	(inoue.in. and wafer) and identification	USPAT	OR	OFF	2002/01/16 13:14
S59	0	inoue-fumihiko.in.	USPAT	OR	OFF	2002/01/16 13:15
S60	3	inoue-fumihiko.in.	USPAT	OR	OFF	2002/01/16 13:16
S61	2	furukawa-hisashi.in.	USPAT	OR	OFF	2002/01/16 13:16
S62	0	kageyama-joichiro.in.	USPAT	OR	OFF	2002/01/16 13:17
S63	20	shiba-tetsuo.in.	USPAT	OR	OFF	2002/01/16 13:19
S64	4	yajima-takashi.in.	USPAT	OR	OFF	2002/01/16 13:20
S65	305	wafer and boule	USPAT	OR	OFF	2002/01/16 13:20
S66	9	(wafer and boule) and ion adj implant	USPAT	OR	OFF	2002/01/16 13:22
S67	2	wafer adj5 identification same boule	USPAT	OR	OFF	2002/01/16 13:22
S68	2	("4010355") or ("4585931").PN.	USPAT; USOCR	OR	OFF	2002/01/16 13:59
S69	26	"4585931".URPN.	USPAT	OR	OFF	2002/01/16 14:01
S70	15	"4010355".URPN.	USPAT	OR	OFF	2002/01/16 14:09
S71	851	boule	USPAT	OR	OFF	2002/01/16 14:52
S72	310	boule and slic\$4	USPAT	OR	OFF	2002/01/16 14:52
S73	132	boule adj25:slic\$4	USPAT	OR	OFF	2002/01/16 14:52
S74	2	(boule adj25 slic\$4) same identif\$4	USPAT	OR	OFF	2002/01/16 14:53
S75	21	"4418467".URPN.	USPAT	OR	OFF	2002/01/17 08:52
S76	351	wafer adj dicing	USPAT	OR	OFF	2002/01/17 08:58
S77	3	(wafer adj dicing) and boule	USPAT	OR	OFF	2002/01/17 08:59
S78	1810	wafer adj align\$4	USPAT	OR	OFF	2002/01/17 09:05
S79	1	(wafer adj align\$4) same boule	USPAT	OR	OFF	2002/01/17 09:01
S80	3	("3652145" "4138189" "4674824").PN.	USPAT	OR	OFF	2002/01/17 09:01
S81	6	(wafer adj align\$4) and boule	USPAT	OR	OFF	2002/01/18 10:37

S82	554	(process\$4 adj5 wafer) adj25 align\$4	USPAT	OR	OFF	2002/01/17 09:06
S83	0	((process\$4 adj5 wafer) adj25 align\$4) and boule	USPAT	OR	OFF	2002/01/17 09:06
S84	133	((process\$4 adj5 wafer) adj25 align\$4) and completion	USPAT	OR	OFF	2002/01/17 09:06
S85	24	((process\$4 adj5 wafer) adj25 align\$4) and completion) and ion	USPAT	OR	OFF	2002/01/17 09:06
S86	1	("5792566").PN.	USPAT; USOCR	OR	OFF	2002/01/18 10:37
S87	2	"5792566".URPN.	USPAT	OR	OFF	2002/01/18 10:37
S88	5	("2442755" "2543071" "4442178" "5769941" "5792566").PN.	USPAT	OR	OFF	2002/01/18 10:37
S89	7	("4084354" "5227339" "5405285" "5439723" "5679060" "5792566" "5927263").PN.	USPAT	OR	OFF	2002/01/18 10:38
S90	2	"5769941".URPN.	USPAT	OR	OFF	2002/01/18 10:43
S91	5	("2442755" "2543071" "4442178" "5769941" "5792566").PN.	USPAT	OR	OFF	2002/01/18 10:45
S92	311	wafer and interference adj fringe	USPAT	OR	OFF	2002/01/22 15:02
S93	77	(wafer and interference adj fringe) and coating	USPAT	OR	OFF	2002/01/22 14:20
S94	46	((wafer and interference adj fringe) and coating) and (sapphire silicon)	USPAT	OR	OFF	2002/01/22 15:16
S95	16	"4864123".URPN.	USPAT	OR	OFF	2002/01/22 14:29
S96	20	"4975141".URPN.	USPAT	OR	OFF	2002/01/22 14:30
S97	1	("6214250").PN.	USPAT; USOCR	OR	OFF	2002/01/22 14:34
S98	1	("6268641").PN.	USPAT; USOCR	OR	OFF	2002/01/22 14:34
S99	1	("4198261").PN.	USPAT; USOCR	OR	OFF	2002/01/22 14:58
S100	1	(wafer and interference adj fringe) and 235/494.ccls.	USPAT	OR	OFF	2002/01/22 15:02
S101	11	((wafer and interference adj fringe) and coating) and (sapphire silicon adj carbide)	USPAT	OR	OFF	2002/01/22 15:16
S102	0	235/492.02.ccls.	USPAT	OR	OFF	2002/01/23 07:40
S103	32	235/462.02.ccls.	USPAT	OR	OFF	2002/01/23 07:40

S10 4	964	wafer and (status near5 process\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/13 09:07
S10 5	15	(wafer and (status near5 process\$4)) and (ion adj1 implant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/13 09:08
S10 6	3	ptis same (numeral\$1 charater\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 07:49
S10 7	1199	pits same (numeral\$1 charater\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 07:49
S10 8	700	kageyama.in.	USPAT	OR	OFF	2002/08/26 07:54
S10 9	25	kageyama.in. and wafer	USPAT	OR	OFF	2002/08/26 13:43
S11 0	73	kageyama.in. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/26 13:43
S11 1	33	("3581100" "3812374" "4019026" "4418467" "4435732" "4444492" "4471385" "4636080" "4672457" "4704027" "4732473" "4769523" "4782751" "4818847" "4864629" "4884178" "4926409" "5048968" "5053612" "5109432" "5149948" "5177346" "5197105" "5231536" "5239169" "5265170" "5371347" "5386481" "5406060" "5449892" "5469294" "5515452" "5585615").PN.	USPAT	OR	ON	2002/08/26 13:56
S11 2	4	"5894348".URPN.	USPAT	OR	ON	2002/08/26 13:58
S11 3	347	scribe adj1 mark	USPAT	OR	OFF	2002/08/27 07:28

S11 4	3	(scribe adj1 mark) and (ion adj1 implant\$3)	USPAT	OR	OFF	2002/08/26 14:01
S11 5	11477	ion adj1 implant\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 16:21
S11 6	0	(scribe adj1 mark) same (ion adj1 implant\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 10:43
S11 7	3	(scribe adj1 mark) and (ion adj1 implant\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 14:44
S11 8	1540	(ion adj1 implant\$1) same wafer\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 14:46
S11 9	0	((ion adj1 implant\$1) same wafer\$1) same pit\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 14:46
S12 0	0	((ion adj1 implant\$1) same wafer\$1) and "235"/\$7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 14:47
S12 1	367	((ion adj1 implant\$1) same wafer\$1) and "438"/\$7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 14:47
S12 2	21	ion adj1 implant\$1 adj1 depth	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 14:50
S12 3	1838	(ion adj1 implant\$1) same etch\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 15:51

S12 4	293	((ion adj1 implant\$1) same wafer\$1) same etch\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 14:51
S12 5	1	(ion adj1 implant\$1) same boule	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 15:53
S12 6	13	(ion adj1 implant\$1) and boule	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 16:12
S12 7	2	("5060043").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/26 16:16
S12 8	1	"5060043".URPN.	USPAT	OR	ON	2002/08/26 16:12
S12 9	10	("4371966" "4542511" "4755314" "5060043" "5187729" "5227339" "5279077" "5284792" "5402239" "5677565").PN.	USPAT	OR	ON	2002/08/26 16:14
S13 0	9	(laser adj1 read\$3) same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 10:25
S13 1	351	(ion adj1 implant\$1) same coat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 16:22
S13 2	0	((ion adj1 implant\$1) same coat\$3) same pit\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/26 16:22
S13 3	7	((ion adj1 implant\$1) same coat\$3) same code	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 06:53

S13 4	122	quaternary adj1 code\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:20
S13 5	13	(quaternary adj1 code\$3) and circle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 06:56
S13 6	1103	circle same oval same rectangle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 06:56
S13 7	7	(circle same oval same rectangle) same code	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 06:56
S13 8	403	scribe adj1 mark	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/27 07:28
S13 9	0	(scribe adj1 mark) same (ion adj1 implant\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 09:52
S14 0	1458	wafer same (ion adj1 implant\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/27 07:29
S14 1	0	(wafer same (ion adj1 implant\$1)) same pit\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/27 07:38
S14 2	10	(wafer same (ion adj1 implant\$1)) same code\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/27 07:29
S14 3	0	((wafer same (ion adj1 implant\$1)) same etch\$3) same contrast	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/27 07:38

S14 4	278	(wafer same (ion adj1 implant\$1)) same etch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/27 07:39
S14 5	31	(laser adj1 read\$3)adj1 device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 10:26
S14 6	110	(scribe adj1 mark) same (coat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 10:44
S14 7	1	((scribe adj1 mark) same (coat\$3)) same (sapphire silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 10:46
S14 8	16	((scribe adj1 mark) same (coat\$3)) and (sapphire silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/27 10:47
S14 9	3	(((scribe adj1 mark) same (coat\$3)) and (sapphire silicon)) and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/28 08:47
S15 0	2	("4256514").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 08:47
S15 1	90	"4256514":URPN.	USPAT	OR	ON	2002/08/28 08:50
S15 2	30	(scribe adj1 mark) same (wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:13
S15 3	22	((scribe adj1 mark) same (wafer)) and reference	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:36

S15 4	21953	interferometer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:37
S15 5	1861	interferometer same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:45
S15 6	0	(interferometer same wafer) same (linear adj1 diode\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:38
S15 7	17	(interferometer same wafer) same (diode\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:39
S15 8	1	(interferometer same wafer) same (diode\$1 adj1 array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:40
S15 9	39	interferometer same (diode\$1 adj1 array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:40
S16 0	0	((scribe adj1 mark) same (wafer)) and (interferometer same wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:45
S16 1	0	(scribe adj1 mark) same (interferometer same wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 10:46
S16 2	5	(information adj1 mark) same (interferometer same wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:13
S16 3	8	(scribe adj1 mark) near form\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:15

S16 4	16	wafer same process\$4 same alter\$3 same record\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:25
S16 5	0	wafer same updat\$4 same (pit\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:27
S16 6	0	wafer same updat\$4 same (scribe adj1 mark\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:28
S16 7	0	updat\$4 same (scribe adj1 mark\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:28
S16 8	2	append\$4 same (scribe adj1 mark\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 11:28
S16 9	14	add\$3 same (scribe adj1 mark\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 12:53
S17 0	1065	438/15,16.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 12:53
S17 1	218	438/15,16.ccls. and depth	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 12:58
S17 2	114	(438/15,16.ccls. and depth) and region	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 12:54
S17 3	6	((438/15,16.ccls. and depth) and region) and pit\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 12:56

S17 4	8	438/15,16.ccls. and ion adj implant\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 12:57
S17 5	1	contrast\$3 near5 (ion adj implant\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 12:57
S17 6	124	438/15,16.ccls. and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 12:59
S17 7	56	(438/15,16.ccls. and record\$3) and append\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:02
S17 8	127618	code\$3 and append\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:02
S17 9	6321	code\$3 near5 append\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:05
S18 0	3	(code\$3 near5 append\$3) same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:03
S18 1	91	pit\$3 near5 append\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:05
S18 2	7493	code\$3 near5 updat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:05
S18 3	0	(pit\$3 near5 append\$3) same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:05

S18 4	4	(code\$3 near5 updat\$4) same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:09
S18 5	7	("5231585" "5537325" "5751581" "5886896" "5972727" "6040095" "6240335").PN.	USPAT	OR	ON	2002/08/28 13:07
S18 6	1036	235/494.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:10
S18 7	72	235/494.ccls. and updat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:10
S18 8	19	235/494.ccls. and ((updat\$4 append\$4) adj5 code\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:36
S18 9	27	("4271210" "4327283" "4515867" "4672600" "4775786" "4861620" "4888475" "4971858" "4983555" "5008151" "5027151" "5042925" "5204163" "5262628" "5268562" "5273798" "5326627" "5362554" "5366682" "5407474" "5434113" "5446338" "5465780" "5484099" "5521371" "5521709" "5780142").PN.	USPAT	OR	ON	2002/08/28 13:34
S19 0	11307	ion adj1 implant\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:37
S19 1	1458	(ion adj1 implant\$1).same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:37

S19 2	3	((ion adj1 implant\$1) same wafer) same contrast	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:40
S19 3	10	((ion adj1 implant\$1) same wafer) same code\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/28 13:41
S19 4	9	(quaternary adj1 code\$3) same shape\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:25
S19 5	0	(quaternary adj1 code\$3) same rectangle\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:22
S19 6	0	(quaternary adj1 code\$3) same oval\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:22
S19 7	1108	oval\$1 same circle\$1 same rectangle\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:44
S19 8	11	(oval\$1 same circle\$1 same rectangle\$1) same code\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:24
S19 9	0	(oval\$1 same circle\$1 same rectangle\$1) and (quaternary adj1 code\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:44
S20 0	122	(quaternary adj1 code\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 13:32
S20 1	2	(quaternary adj1 code\$3) same graphic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:43

S20 2	49	(oval\$1 same circle\$1 same rectangle\$1) and quaternary	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:46
S20 3	1	(oval\$1 same circle\$1 same rectangle\$1) and 235/494.ccis.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:47
S20 4	1	((quaternary adj1 code\$3)) and 235/494.ccis.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:50
S20 5	3	("5264386" "5330924" "5576573").PN.	USPAT	OR	ON	2002/08/29 10:48
S20 6	0	"5834819".URPN.	USPAT	OR	ON	2002/08/29 10:49
S20 7	4608	multi adj5 code\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:50
S20 8	0	((multi adj shape\$1) multi-shape\$1) adj5 code\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 10:50
S20 9	37	(multi adj5 code\$1) and 235/494.ccis.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 14:22
S21 0	0	(quaternary adj1 code\$3)and (different adj1 shape\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 13:35
S21 1	122	quaternary adj1 code\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 13:34
S21 2	9	(quaternary adj1 code\$3) same (shape\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 13:35

S21 3	931	code near shape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 14:23
S21 4	65	(code near shape) and "235"/\$7 ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 14:44
S21 5	2	("6195323").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/29 14:51
S21 6	4	("5446717" "5761172" "5796692" "6023447").PN.	USPAT	OR	ON	2002/08/29 14:45
S21 7	403	wafer same boule	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 14:55
S21 8	0	boule\$1 adj1 sequence\$1 adj1 notch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 14:53
S21 9	0	boule\$1 adj1 notch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 14:53
S22 0	11	(wafer same boule) same notch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/08/29 14:53
S22 1	2	("5792566").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/08/29 14:56
S22 2	5	("3507426" "3743148" "4442178" "4632884" "4755314").PN.	USPAT	OR	ON	2002/08/29 14:56
S22 3	17	"3507426".URPN.	USPAT	OR	ON	2002/08/29 14:56
S22 4	2	"5792566".URPN.	USPAT	OR	ON	2002/08/29 14:57

S22 5	7	("4084354" "5227339" "5405285" "5439723" "5679060" "5792566" "5927263").PN.	USPAT	OR	ON	2002/08/29 14:57
S22 6	16	"4084354".URPN.	USPAT	OR	ON	2002/08/29 14:59
S22 7	3	("3039235" "3626644" "3662733").PN.	USPAT	OR	ON	2002/08/29 15:00
S22 8	264	wafer near20 identification near20 mark	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/10 10:51
S22 9	7	(wafer near20 identification near20 mark) and "235"/\$7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/06/10 10:51
S23 0	2	("5792566").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/16 06:04
S25 1	5	sapphire same coating same pits	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:25
S25 2	12	(silicon adj carbide) same coating same pits	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:27
S25 3	81996	(silicon adj carbide)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:27
S25 4	1	S253 same barcode	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:28
S25 5	52	S253 same code	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:31
S25 6	0	S255 same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:31

S25 7	11	S255 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:30
S25 8	14459	S253 same coat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:31
S25 9	7969	S253 near10 coat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:31
S26 0	462	S259 same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:31
S26 1	0	S260 same code	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:31
S26 2	18	S260 and code	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:58
S26 3	96	wafer same coat\$4 same code	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 08:04
S26 4	0	S263 same sapphire	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 08:00
S26 5	0	S263 same carbide	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:58
S26 6	2	S263 and carbide	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 07:58
S26 7	6	S263 and sapphire	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/06/27 08:00